

# Single N-channel MOSFET

## ELM13406CA-S

### ■ General description

ELM13406CA-S uses advanced trench technology to provide excellent  $R_{ds(on)}$ , low gate charge and low gate resistance.

### ■ Features

- $V_{ds}=30V$
- $I_d=3.6A$  ( $V_{gs}=10V$ )
- $R_{ds(on)} < 65m\Omega$  ( $V_{gs}=10V$ )
- $R_{ds(on)} < 105m\Omega$  ( $V_{gs}=4.5V$ )

### ■ Maximum absolute ratings

Parameter	Symbol	Limit	Unit	Note
Drain-source voltage	$V_{ds}$	30	V	
Gate-source voltage	$V_{gs}$	$\pm 20$	V	
Continuous drain current Ta=25°C	$I_d$	3.6	A	1
Ta=70°C		2.9		
Pulsed drain current	$I_{dm}$	15	A	2
Power dissipation Ta=25°C	$P_d$	1.4	W	1
Ta=70°C		0.9		
Junction and storage temperature range	$T_j, T_{stg}$	-55 to 150	°C	

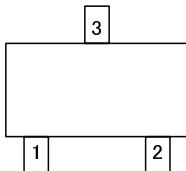
### ■ Thermal characteristics

Parameter		Symbol	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	t≤10s	$R_{\theta ja}$	70	90	°C/W	1
Maximum junction-to-ambient	Steady-state		100	125	°C/W	
Maximum junction-to-lead	Steady-state	$R_{\theta jl}$	63	80	°C/W	3

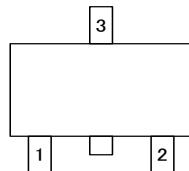
### ■ Pin configuration

### ■ Circuit

SOT-23 (TOP VIEW)

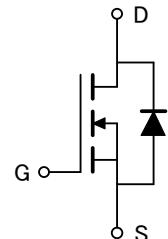


(Without extra bar)



(With extra bar)

Pin No.	Pin name
1	GATE
2	SOURCE
3	DRAIN



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### ■ Electrical characteristics

$T_a=25^\circ C$

Parameter	Symbol	Condition		Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>							
Drain-source breakdown voltage	BVdss	Id=250 $\mu A$ , Vgs=0V		30			V
Zero gate voltage drain current	Idss	Vds=24V				1	$\mu A$
		Vgs=0V	Tj=55°C			5	
Gate-body leakage current	Igss	Vds=0V, Vgs=±20V				100	nA
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=250 $\mu A$		1.0	1.9	3.0	V
On state drain current	Id(on)	Vgs=10V, Vds=5V		15			A
Static drain-source on-resistance	Rds(on)	Vgs=10V			50	65	$m\Omega$
		Id=3.6A	Tj=125°C		74	100	
		Vgs=4.5V, Id=2.8A			75	105	
Forward transconductance	Gfs	Vds=5V, Id=3.6A			7		S
Diode forward voltage	Vsd	Is=1A			0.79	1.00	V
Max. body-diode continuous current	Is					2.5	A
<b>DYNAMIC PARAMETERS</b>							
Input capacitance	Ciss	Vgs=0V, Vds=15V, f=1MHz			288	375	pF
Output capacitance	Coss				57		pF
Reverse transfer capacitance	Crss				39		pF
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz			3	6	$\Omega$
<b>SWITCHING PARAMETERS</b>							
Total gate charge (10V)	Qg	Vgs=10V, Vds=15V, Id=3.6A			6.5	8.5	nC
Total gate charge (4.5V)	Qg				3.1	4.0	nC
Gate-source charge	Qgs				1.2		nC
Gate-drain charge	Qgd				1.6		nC
Turn-on delay time	td(on)	Vgs=10V, Vds=15V RL=2.2 $\Omega$ , Rgen=3 $\Omega$			4.6		ns
Turn-on rise time	tr				1.9		ns
Turn-off delay time	td(off)				20.1		ns
Turn-off fall time	tf				2.6		ns
Body diode reverse recovery time	trr	If=3.6A, dl/dt=100A/ $\mu s$			10.2	14.0	ns
Body diode reverse recovery charge	Qrr	If=3.6A, dl/dt=100A/ $\mu s$			3.5		nC

### NOTE :

1. The value of  $R\theta_{ja}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board of 2oz. Copper, in still air environment with  $T_a=25^\circ C$ . The value in any given applications depends on the user's specific board design, The current rating is based on the  $t \leq 10s$  thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The  $R\theta_{ja}$  is the sum of the thermal impedance from junction to lead  $R\theta_{jl}$  and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80  $\mu s$  pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25^\circ C$ . The SOA curve provides a single pulse rating.

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## ■ Typical electrical and thermal characteristics

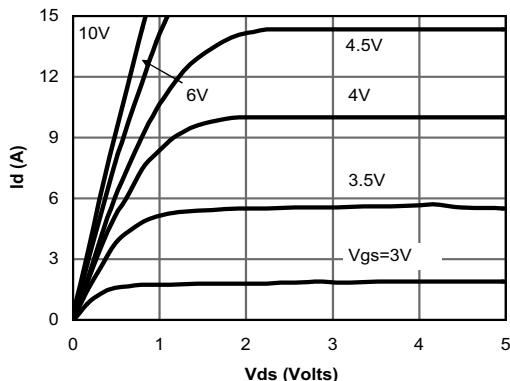


Fig 1: On-Region Characteristics

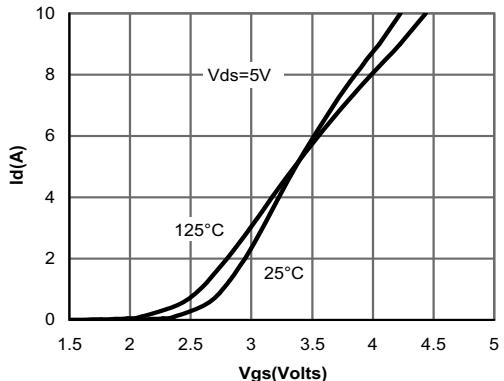


Figure 2: Transfer Characteristics

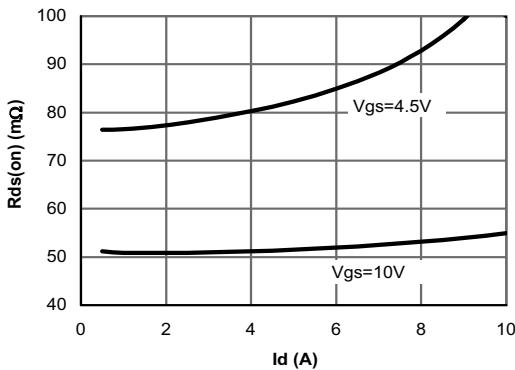


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

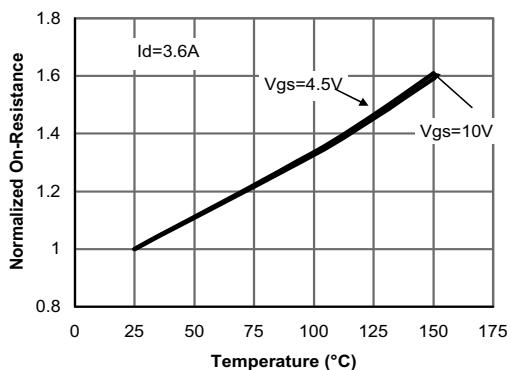


Figure 4: On-Resistance vs. Junction Temperature

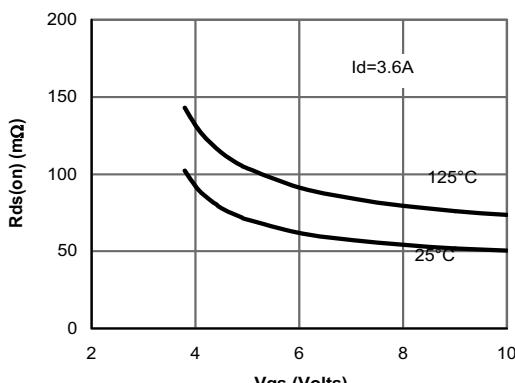


Figure 5: On-Resistance vs. Gate-Source Voltage

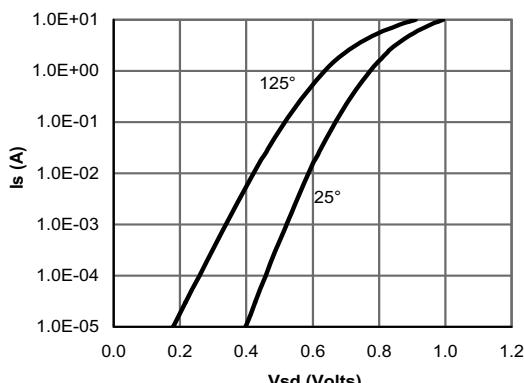


Figure 6: Body-Diode Characteristics

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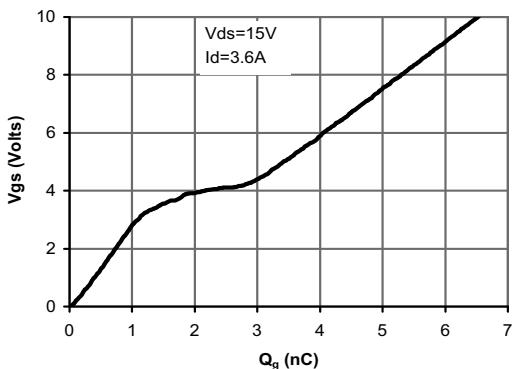


Figure 7: Gate-Charge Characteristics

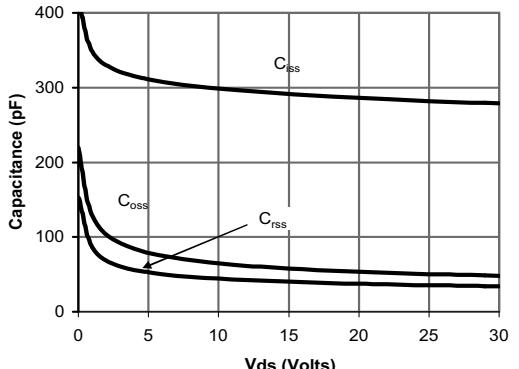


Figure 8: Capacitance Characteristics

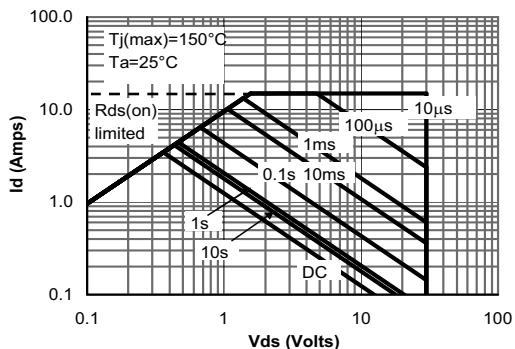


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

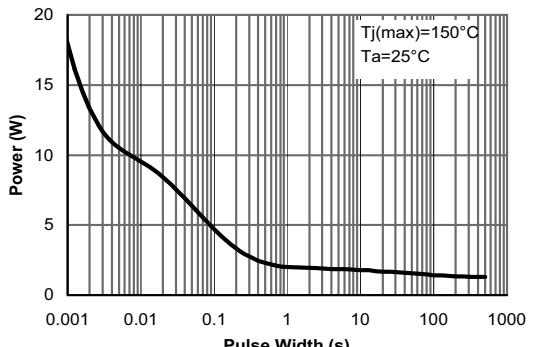


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

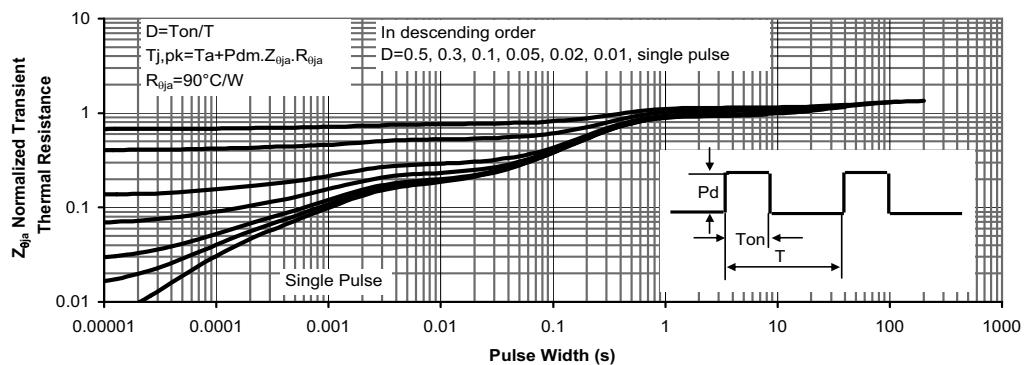


Figure 11: Normalized Maximum Transient Thermal Impedance